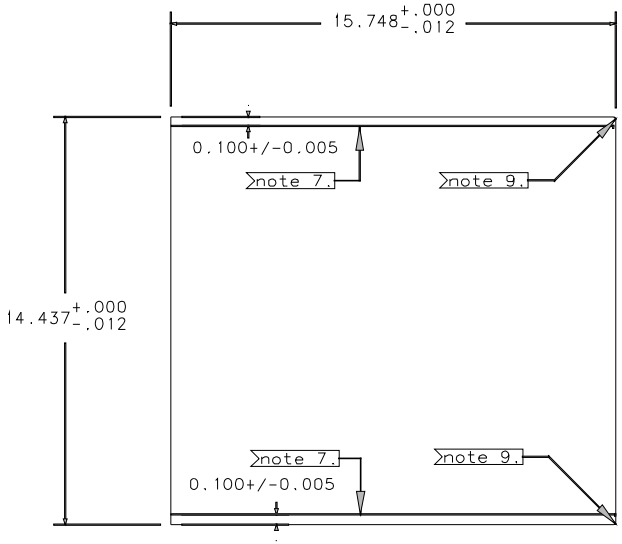
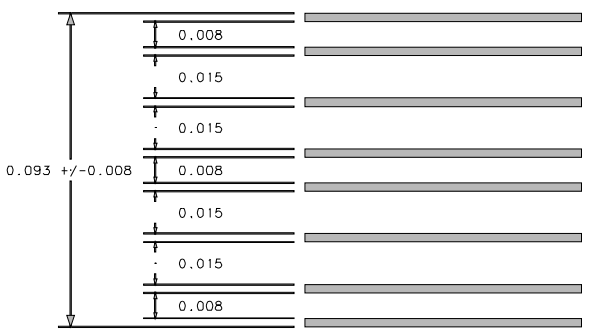


Layer Order



DIRAC BOARD's DRILL SCHEDULE (inches)

SYMBOL	FHS	COUNT	PLATED	COMMENT
○	.018	5469	YES	
⊞	.0236	378	YES	Note 12.
⌀	.035	240	YES	
⊟	.041	453	YES	
⊖	.057	9	YES	
◫	.106	19	NO	
⊕	.113	6	NO	

Note 12: This is a pressfit technology thru hole with the following specification:
12-1. Finished hole size : 0.6mm +/- 0.05mm
12-2. Drilled hole size: 0.7mm +/- 0.02mm
12-3. Thickness of thru hole plating: min 25 μm Cu
12-4. Inside thru hole: OSP with 0.12 - 0.15 μm.

Board Characteristics :

0. All dimensions are given in inches unless specified otherwise.
1. Material FR4 Tg > 170 C.
2. Minimum trace width 0.007" on all layers.
3. Minimum Clearence 0.007" on all layers.
4. 1 oz copper for all Trace and Power Layers.
5. Apply ENTEC or equivalent Organic Coating over bare copper. Apply Solder Mask over bare copper.
6. Board Thickness: 0.093 +/- 0.008".
7. Mill the Top and Bottom of board on the solder side to a thickness of 0.062" +/- 0.008".
8. Silkscreen on Component and Solder Sides.
9. 45 degree chamfer.
10. Hole diameter tolerances : +/- 0.002" unless specified otherwise.
11. Interlayer spacing: as specified.

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE: FRACTIONS DECIMALS ANGLES .XX .XXX DO NOT SCALE DRAWING
TREATMENT
FINISH
SIMILAR TO | ACT. WT | CALC WT

CONTRACT NO.

APPROVALS	DATE
DRAWN M.Bogdan	4/1/99
CHECKED H.Sanders	4/1/99
ISSUED	

UNIVERSITY OF CHICAGO
ELECTRONICS DEVELOPMENT GROUP

TITLE: CDF L1 DIRAC Board Specification Drawing

SIZE B | FSCM NO. | DWG. NO. B - 2352 | REV. E

SCALE 1/4 | SHEET 1 of 1

THIS SHEET IS COMPUTER GENERATED